Pick-up Tool

ABSTRACT

A pick-up tool for the mounting of semiconductor chips onto a substrate has a suction device which consists of a plate (4) made out of a dimensionally stable material one surface of which (5) has structures (6) made of hardened adhesive. The material for the plate (4) is, for example, aluminium, a carbon fibre composite material or a dimensionally stable plastic. A suitable material for the structures (6) is, for example, an adhesive which has Teflon® as the filling material.

(Fig. 1)